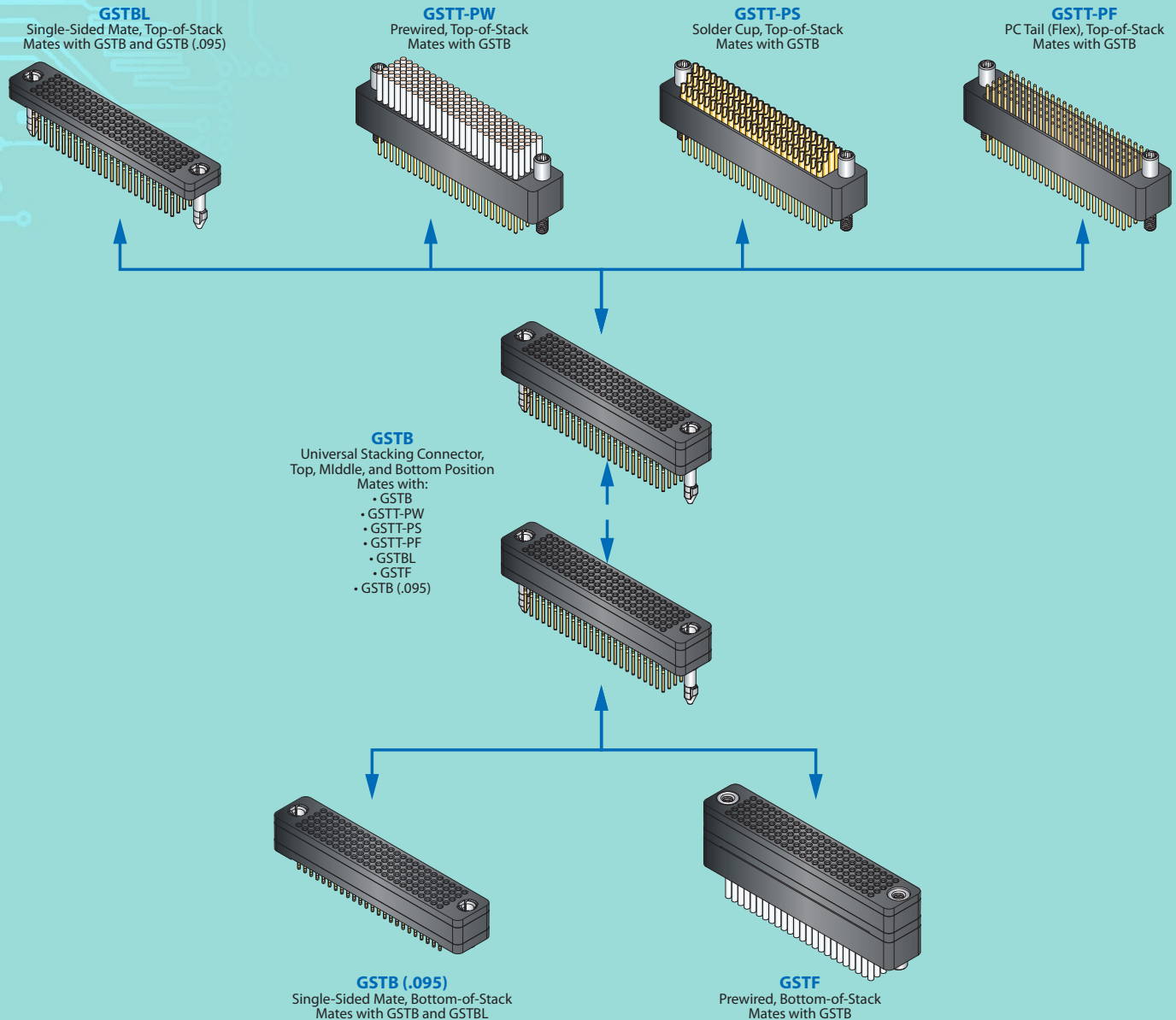


.062" PITCH COMPLIANT PIN High-Density Stacker™

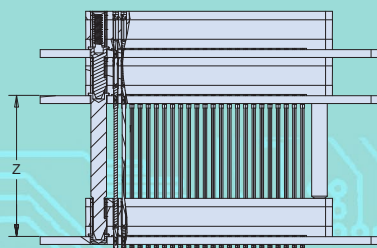


Solder-free, rugged board-to-board
stackable connectors

HD STACKER™ POSITION AND MATING COMPATIBILITY GUIDE



980-008 Between-board spacers available for all GSTB pin lengths.



"Z" Value with associated Termination Length							
Z		Termination Length		Z		Termination Length	
in	mm	in	mm	in	mm	in	mm
.348/.384	8.84/9.75	.270	6.86	.685/.784	17.40/19.91	.600	15.24
.385/.434	9.78/11.02	.300	7.62	.785/.884	19.94/22.45	.700	17.78
.435/.484	11.05/12.29	.350	8.89	.885/.984	22.48/24.99	.800	20.32
.485/.584	12.32/14.83	.400	10.16	.985/1.084	25.02/27.53	.900	22.86
.585/.684	14.86/17.37	.500	12.70	1.085/1.184	27.56/30.10	1.000	25.40

High-Density Stacker™



Solder-free, rugged board-to-board stackable connectors

PERFORMANCE SPECIFICATIONS

DWV: 638 VAC sea level

5000 Megohms minimum @ 500 VDC

Operating temperature: -65°C to +125°C

(4 ounces) X (number of contacts)

(22.5 pounds) X (number of contacts)

MATERIALS AND FINISHES

Contacts: Copper alloy, gold over nickel plating

Encapsulant: Epoxy resin Hysol EE4215

PCB REQUIREMENTS

Board thickness: .058" minimum

Plating material: Sn alloy or ENIG recommended

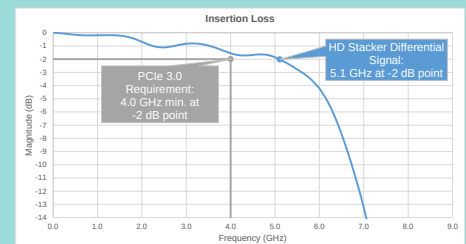
QUALIFICATION TESTING / HIGH-SPEED PERFORMANCE

Stacker connectors were qualified in accordance with MIL-DTL-55302G testing for:

- Contact engagement/separation and retention
- DWV
- Electrical resistance
- Mechanical vibration/shock
- Insulation resistance
- Thermal shock
- Contact resistance
- Humidity

High-frequency electrical performance tests were performed for: Insertion loss, return loss, crosstalk, and time domain performance metrics including impedance and eye pattern.

Complete test reports are available at www.glenair.com/technical_information_test_reports



HD Stacker insertion loss compared to PCIe Rev. 3

PCB LAYOUTS (COMPONENT SIDE)

